



EP250 EPOXY PREPREG

EP250 is a low temperature curing epoxy prepreg that cures in the 250 to 275° F range. EP250 provides outstanding strength and stiffness making it suitable for a wide variety of structural applications. EP250 has good dielectric properties, making it suitable for use in radomes.

Properties of EP250-7781

Tensile Strength, psi	84,000
Tensile Modulus, psi	4,200,000
Tensile Strain at Failure	1.8%
Flexural Strength, psi	74,000
Flexural Modulus, psi	4,100,000
Interlaminar Shear Strength, psi	5,500
Barcol Hardness	70
Dielectric Constant at 7.7 GHZ	4.57
Loss Tangent at 7.7 GHZ	0.012

Process Information - EP250

- Apply Vacuum Bag in Oven Cycle
- 5° F/Minute Ramp to 175° F (Part Temperature)
- Hold for 30 Minutes
- 5° F/Minute Ramp to 250° F– 260° F (Part Temperature)
- Hold at 250° F for Two (2) Hours
- Cool to less than 180° F at 3 to 5° F/Minute
- Release Pressure/Vacuum and Demold

(Higher Cure Temperatures can be used up to 275° F: Hold for 1 ½ Hours at 275° F)

Recommended Storage

- Room Temperature (77° F)	Ten (10) Days
- 40° F	Six (6) Months
- 0° F	Twelve (12) Months

NOTE: EP250 Prepreg is wound with a polyethylene film interliner for easy release. The rolls are sealed in polyethylene film bags to protect prepreg from moisture and other contaminants. The bags should remain sealed while the prepreg is under refrigeration and only removed when the prepreg has had sufficient time to warm to room temperature. When not in use, the prepreg should be returned to refrigerated storage. Care should be exercised to limit out-time of the prepreg in order to insure maximum shelf life. Torn bags should be replaced.

NOTE: The data presented herein has been developed under controlled manufacturing and test conditions and is considered accurate. No warranty is expressed or implied regarding the accuracy or use of this data or the use of this product. It is the responsibility of the end user to determine suitability for use.